

	Hits	Search Text	DBs
19	31	((semiconductor or wafer or substrate or wafer or sensor or device) near14 (die or circuit\$5 or (integrated near9 circuit\$4) or (imag\$4 near9 circuit\$5) or image)) and ((cover or lid or plate or template) same (encapsula\$5 or packa\$4 or mount\$4) same (shield\$4 or (transparent near9 region) or support or (spac\$4 near9 structure) or aperture) same (photosensitive or photoimageable or photosensitive or photoimag\$4) same (pattern\$4 or silk\$4screen\$4 or lithograph\$4 or photolithograph\$4)) and ((encapsulat\$4 near9 packag\$4) or housing or packag\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
20	20	((semiconductor or wafer or substrate or wafer or sensor or device) near14 (die or circuit\$5 or (integrated near9 circuit\$4) or (imag\$4 near9 circuit\$5) or image)) and ((cover or lid or plate or template or protective or shield\$4) same (encapsula\$5 or packa\$4 or mount\$4) same (support or (spac\$4 near9 structure)) same (photosensitive or photoimageable or photosensitive or photoimag\$4) same (pattern\$4 or silk\$4screen\$4 or lithograph\$4 or photolithograph\$4)) and ((encapsulat\$4 near9 packag\$4) or housing or packag\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
21	16	((semiconductor or wafer or substrate or wafer or sensor or device) near14 (die or circuit\$5 or (integrated near9 circuit\$4) or (imag\$4 near9 circuit\$5))) and ((cover or lid or (protective near9 (layer or coat\$4)) or encapsulant) same (mount\$4 or position\$4) same ((transparent near9 region) or transmissive) same (support or (spac\$4 near9 structure) or spacer) same (height or gap or space or distance or depth) same (substrate or imag\$3 near4 circuit\$4 or die or (wafer near9 dice) or circuit\$4 or device))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
22	13	((semiconductor or wafer or substrate or wafer or sensor or device) near14 (die or circuit\$5 or (integrated near9 circuit\$4) or (imag\$4 near9 circuit\$5))) and ((cover or lid or (protective near9 (layer or coat\$4)) or encapsulant) same ((transparent or transmissive or transmitting) near9 (portion or region or area)) same (support or (spac\$4 near9 structure) or spacer) same (height or thickness) same (gap or spac\$3 or distance or depth) same ((imag\$3 near4 circuit\$4) or circuit\$3 or die or (wafer near9 die)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
23	6	((semiconductor or wafer or substrate or wafer or sensor or device) near14 (die or circuit\$5 or (integrated near9 circuit\$4) or (imag\$4 near9 circuit\$5))) and ((cover or lid or (protective near9 (layer or coat\$4)) or encapsulant) same ((transparent or transmissive or transmitting) near9 (portion or region or area)) same (support or (spac\$4 near9 structure) or spacer) same (height or thickness) same (gap or spac\$3 or distance or depth) same ((imag\$3 near4 circuit\$4) or circuit\$3 or die or (wafer near9 die)))	US-PGPUB
24	17	((semiconductor or wafer or substrate or wafer or sensor or device) near14 (die or circuit\$5 or (integrated near9 circuit\$4) or (imag\$4 near9 circuit\$5))) and ((cover or lid or (protective near9 (layer or coat\$4)) or encapsulant) same (transparent or transmissive or transmitting) same (support or (spac\$4 near9 structure) or spacer) same (photosensitive or photocur\$4 or photoresist or resist) same (adhesiv\$4 or glue))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
25	55	((semiconductor or wafer or substrate or wafer or sensor or device) near14 (die or circuit\$5 or (integrated near9 circuit\$4) or (imag\$4 near9 circuit\$5))) and ((cover or lid or (protective near9 (layer or coat\$4)) or encapsulant) same (transparent or transmissive or transmitting) same (support or (spac\$4 near9 structure) or spacer or seal) same (photosensitive or photocur\$4 or photoresist or resist) same (pattern\$\$ or photolithograph\$6 or lithograph\$6))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
26	25	((semiconductor or wafer or substrate or wafer or sensor or device) near14 (die or circuit\$5 or (integrated near9 circuit\$4) or (imag\$4 near9 circuit\$5))) and ((function\$4 or circuit\$4 or die) same (cover or lid or (protective near9 (layer or coat\$4)) or encapsulant) same (transparent or transmissive or transmitting) same (support or (spac\$4 near9 structure) or spacer or seal) same (photosensitive or photocur\$4 or photoresist or resist) same (pattern\$4 or photolithograph\$6 or lithograph\$6))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
27	152	((epoxy near16 resin\$4) same (glue or seal\$4 or adhesive\$5) same (photosensitive or photoreactive or photoresist) same pattern\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
28	48	((top or protective or sheet or template or lid or cover) same (glue or seal\$4 or adhesive\$5) same (photosensitive or photoreactive or photoresist) same pattern\$4 same (support or spacer or structure)) and ((top or protective or lid or sheet or template or cover) same (transmissive or transparent or translucent) same (die or circuit\$4 or function\$4 or imag\$4))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
29	19	((top or protective or sheet or template or lid or cover) same (glue or seal\$4 or adhesive\$5) same (photosensitive or photoreactive or photoresist) same pattern\$4 same (support or spacer or structure)) and ((top or protective or lid or sheet or template or cover) same (transmissive or transparent or translucent) same (die or circuit\$4 or function\$4 or imag\$4)) and (encapsulat\$4 or encapsulant or packag\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB